

Zener Diode DZ2W04700L

Unit: mm

0.13

DZ2W04700L Silicon epitaxial planar type

For constant voltage / For surge absorption circuit DZ24047 in Mini2 type package

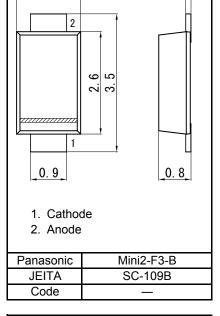
Features

- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: AJ

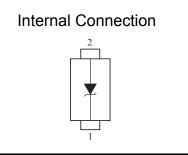
Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25	°C		
Parameter	Symbol	Rating	Unit
Repetitive peak forward current	IFRM	500	mA
Forward current	IF	200	mA
Total power dissipation ^{*1}	PT	1	W
Non-repetitive reverse power surge *2	PZSM	100	W
Electrostatic discharge *3	ESD	±30	kV
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C
Note: *1 Mounted on ceramics print circuit bo	ard.		
Board size: 50 mm × 50 mm			
Board thickness: 0.8 mm			



1.6



*2 t = 0.1ms
*3 Test method:IEC61000_4_2(C = 150 pF,R = 330 Ω, Contact discharge:10 times)

■ Electrical Characteristics Ta = 25 °C ± 3 °C

Soldering size: 2 mm × 2 mm

Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Forward voltage	VF	IF = 200 mA			1.2	V	
Zener voltage *1, *2	VZ	IZ = 20 mA	4.47	4.70	4.94	V	
Zener operating resistance	RZ	IZ = 20 mA			60	Ω	
Reverse current	IR	VR = 1 V			40	μA	
Temperature coefficient of zener voltage *3	SZ	IZ = 20 mA		-0.8		mV/°C	

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. Absolute frequency of input and output is 5 MHz.

3. *1 The temperature must be controlled 25°C for VZ mesurement.

VZ value measured at other temperature must be adjusted to VZ (25°C)

*2 VZ guaranted 20 ms after current flow.

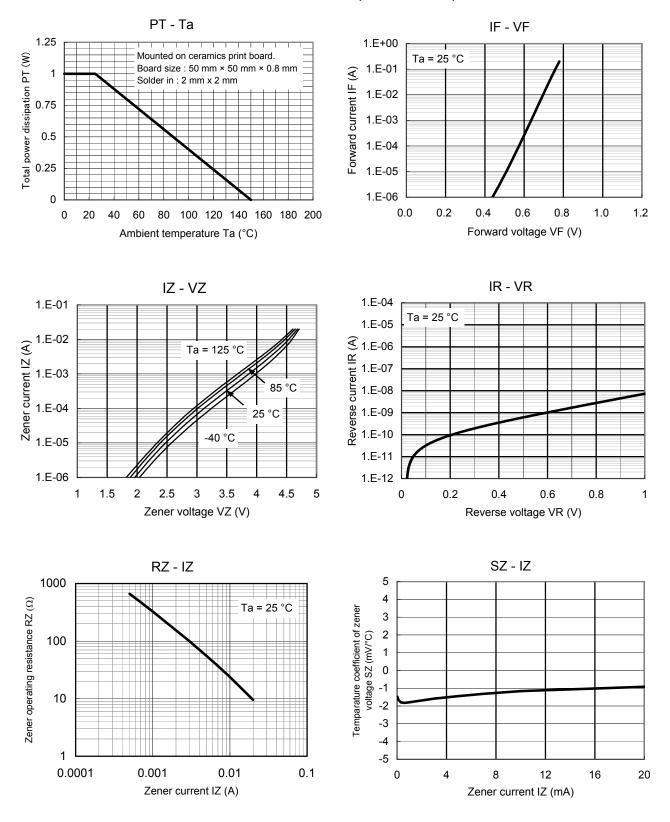
*3 Tj = 25°C to 150°C

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Technical Data (reference)





2000

1500

1000

500

0

0

1

Terminal capacitance Ct (pF)

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Board size : 50 mm × 50 mm x 0.8 mm

10

100

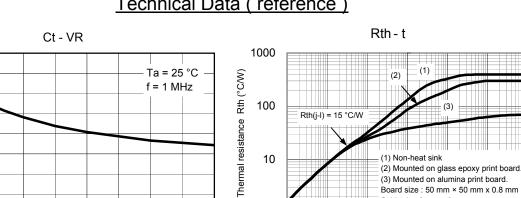
ш

1000

Solder in : 2 mm x 2 mm

1

Time t (s)



4

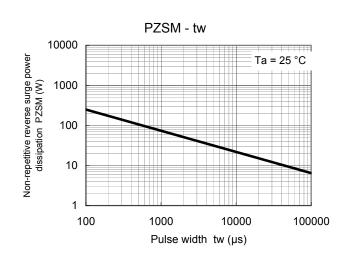
1

0.001

0.01

0.1

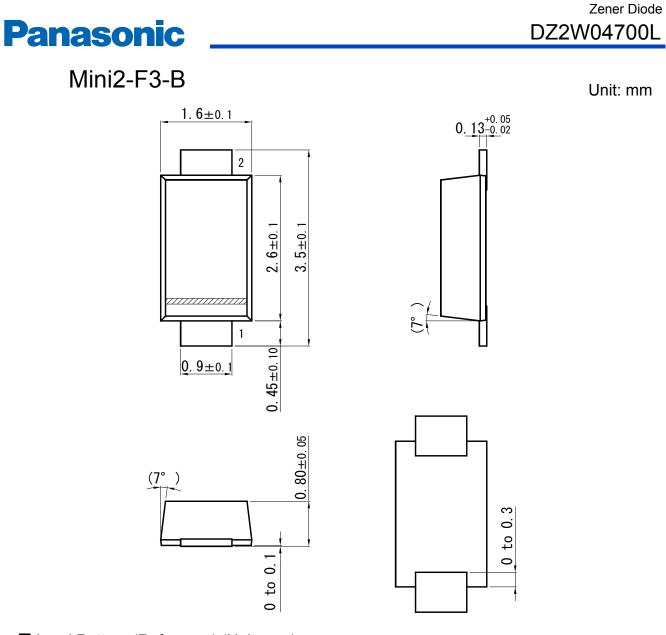
Technical Data (reference)

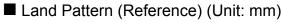


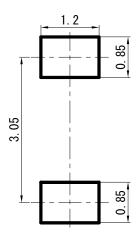
2

Reverse voltage VR (V)

3







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